We claim

1. An electrostatic discharge (ESD) protection structure for protecting an Integrated Circuit comprising:

a first semiconductor region of a first conductivity type;

a second semiconductor region of a second conductivity type adjacent said first semiconductor region;

a third semiconductor region of a first conductivity type adjacent said second semiconductor region;

a fourth semiconductor region of a second conductivity type adjacent said third semiconductor region; and

a fifth semiconductor region of a first conductivity type adjacent said second fourth semiconductor region; wherein a first terminal, A, of said ESD structure is connected to said first semiconductor region and a second terminal, K, of said ESD structure is connected to said fifth semiconductor region.

2. The ESD structure of Claim 1, wherein said first conductivity type is an n-type semiconductor and said second conductivity type is a p-type semiconductor.

3. The ESD structure of Claim 1, wherein said first conductivity type is a p-type semiconductor and said second conductivity type is an n-type semiconductor.

4. The ESD structure of Claim 2 wherein said first and said second semiconductor regions are shorted together and wherein said fourth and said fifth semiconductor regions are shorted together.

5. The ESD structure of Claim 4 wherein said third semiconductor region includes an n-well region formed in a p-type semiconductor substrate.

6. The ESD structure of Claim 5 wherein said second and said fourth semiconductor regions each include a p-base region formed in said n-well region.

7. The ESD structure of Claim 6 wherein said first and said fifth semiconductor regions each include an n^+ region formed in one of said p-base regions.

8. The ESD structure of Claim 1 further comprising a first current source connected across terminal A and a first end of a first resistor whose second end is connected to terminal K and a second current source connected across terminal K and a first end of a second resistor whose second end is connected to terminal A.

9. The ESD structure of Claim 7 further comprising a first current source connected across terminal A and a first end of a first resistor whose second end is connected to terminal K and a second current source

connected across terminal K and a first end of a second resistor whose second end is connected to terminal A.

10. The ESD structure of Claim 9 wherein said first and said second current sources each include a pair of back-to-back Zener diodes.

11. A method of protecting an Integrated Circuit against an electro-static discharge (ESD), said method comprising the steps of:

forming a first semiconductor region of a first conductivity type;

forming a second semiconductor region of a second conductivity type adjacent said first semiconductor region;

forming a third semiconductor region of a first conductivity type adjacent said second semiconductor region;

forming a fourth semiconductor region of a second conductivity type adjacent said third semiconductor region;

forming a fifth semiconductor region of a first conductivity type adjacent said fourth semiconductor region;

forming a first terminal over said first semiconductor region and in electrical contact therewith;

forming a second terminal over said fifth semiconductor region and in electrical contact therewith;

forming a low impedance conductive path across said two terminals.

12. The method of Claim 11 wherein the step of forming a third semiconductor region of a first conductivity type includes the step of forming an n-well region in a p-type substrate.

13. The method of Claim 12 wherein the steps of forming a second and a fourth semiconductor regions includes the steps of forming two separate and isolated p-type regions in said n-well.

14. The method of Claim 13 wherein the steps of forming a first and a fifth semiconductor regions includes the steps of forming a n-type semiconductor region in each of said p-type regions.

15. The method of Claim 14 further comprising means for varying a trigger voltage at which said forming a low impedance conductive path across said two terminals occurs.

16. The method of Claim 15 wherein said means includes a current source connected across said first terminal and a first end of a first resistor whose second end is connected to said second terminal and a second current source connected across said second terminal and a first end of a second resistor whose second end is connected to said first terminal.

17. The method of Claim 16 wherein said first and said second current sources each include a pair of back-to-back Zener diodes.

18. An electrostatic discharge (ESD) protection structure comprising:

corner cells, each corner cell comprising a square-shaped semiconductor region of a first conductivity type surrounded on two sides by semiconductor regions of a second conductivity type, said first and said second semiconductor regions both formed in a second square-shaped semiconductor region of the first semiconductor conductivity type, said second square-shaped semiconductor region formed in a third square-shaped semiconductor region of a second conductivity type, said corner cells to form all corners of said ESD structure;

edge cells, each edge cell comprising a square-shaped semiconductor region of a first conductivity type surrounded on three sides by semiconductor regions of a second conductivity type, said first and said second semiconductor regions both formed in a second square-shaped semiconductor region of the first semiconductor conductivity type, said second square-shaped semiconductor region formed in a third square-shaped semiconductor region of a second semiconductor conductivity type, said corner cells to form all edges of said ESD structure;

center cells, each center cell comprising a square-shaped semiconductor region of a first conductivity type surrounded on four sides by semiconductor regions of a second conductivity type, said first and said second semiconductor regions both formed in a second square-shaped semiconductor region of the first conductivity type, said second square-shaped semiconductor region formed in a third square-shaped semiconductor region of a second conductivity type, said center cells to form all portions of said ESD structure which are not formed by said corner cells and said edge cells.

19. The ESD protection structure of Claim 18 wherein said corner cells, said edge cells and said center cells have square geometrical shapes with identical areas.

20. The ESD protection structure of Claim 19 wherein said ESD protection structure has a square geometry.